

Exhibitors' session I 11.09.2017 17.30 – 18.30			
No	Exhibitor	Speaker	Presentation title
1	Poltronic	Paul Collander	Technology transfer and consulting between the Nordic countries and the rest of the world
2	Hirox Europe	Emilien LEONHARDT, Managing Director	Latest trends in 3D digital microscopy for microelectronics and packaging, R&D and QC
3	EV Group	Mr. Harald Wiesbauer, Regional Sales Manager Europe	EVG Nanoimprint Lithography for emerging industrial applications
4	Microdul	Adrian Stalder, Sales Engineer	Short introduction on our capabilities
5	Trelic	Dr. Laura Frisk, CEO of Trelic	Trelic – Your partner with electronics materials, packaging and reliability
6	NAMICS EUROPE GMBH	Sedat Yagci	NAMICS company introduction
Exhibitors' session II 12.09.2017 17.30 – 18.30			
No	Exhibitor	Speaker	Presentation title
7	Micross	Juan Bevan	Micross components company introduction
8	F&S BONDTEC	Christoph Zauner	Presentation of F&S BONDTEC and an introduction of our bondtester portfolio, especially brandnew LAB-Tester LT-101
9	Ferro	Peter van Eijk, account manager Ferro	Ferro company presentation
10	Cybertechnologies	Simon Cannonier – Marketing & Sales Manager	3D surface metrology
11	Sentec Group	Jason Huang - Director	A better beramic substrate for power module
12	Pactech	Sebastian Hahn, Sales Manager	Equipment manufacturing, subcontracting services and chemistry for the microelectronics industry from one single source – PacTech!
13	ISP-System	Jean-Yves Bécél, Export Account Manager	High precision die-bonder & advanced microassembly special machines